

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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30 V, 2 A, Low V_{CE(sat)} PNP Transistor

ON Semiconductor's e^2 PowerEdge family of low $V_{CE(sat)}$ transistors are miniature surface mount devices featuring ultra low saturation voltage ($V_{CE(sat)}$) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical application are DC–DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e²PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

| Rating | Symbol | Max | Unit |
|--------------------------------|------------------|------|------|
| Collector-Emitter Voltage | V_{CEO} | -30 | Vdc |
| Collector-Base Voltage | V _{CBO} | -50 | Vdc |
| Emitter-Base Voltage | V_{EBO} | -5.0 | Vdc |
| Collector Current – Continuous | I _C | -1.0 | Α |
| Collector Current – Peak | I _{CM} | -2.0 | Α |

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Max | Unit |
|--|-----------------------------------|----------------|-------------|
| Total Device Dissipation T _A = 25°C Derate above 25°C | P _D (Note 1) | 310 2.5 | mW mW/°C |
| Thermal Resistance, Junction to Ambient | R _{θJA} (Note 1) | 403 | °C/W |
| Total Device Dissipation T _A = 25°C Derate above 25°C | P _D (Note 2) | 710 5.7 | mW mW/°C |
| Thermal Resistance, Junction to Ambient | R _{θJA} (Note 2) | 176 | °C/W |
| Total Device Dissipation (Single Pulse < 10 sec.) | P _{Dsingle} (Note 3) | 575 | mW |
| Junction and Storage Temperature Range | T _J , T _{stg} | –55 to +150 | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

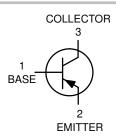
- 1. FR-4 @ Minimum Pad.
- 2. FR-4 @ 1.0 X 1.0 inch Pad.
- 3. Refer to Figure 8.



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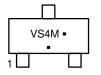
$\begin{array}{c} 30 \text{ VOLTS} \\ 2.0 \text{ AMPS} \\ \text{PNP LOW V}_{\text{CE(sat)}} \text{ TRANSISTOR} \\ \text{EQUIVALENT R}_{\text{DS(on)}} \text{ 200 m} \Omega \end{array}$





SOT-23 (TO-236) CASE 318 STYLE 6

MARKING DIAGRAM



VS4 = Specific Device Code

M = Date Code*

= Pb–Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

| Device | Package | Shipping [†] | | |
|-------------------------------|---------------------|-----------------------|--|--|
| NSS30100LT1G, NSV30100LT1G | SOT-23 (Pb-Free) | 3000/Tape & Reel | | |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS ($T_A = 25$ °C unless otherwise noted)

| Characteristic | Symbol | Min | Max | Unit |
|--|----------------------|------------------------|-------------------------|------|
| OFF CHARACTERISTICS | | | | |
| Collector – Emitter Breakdown Voltage $(I_C = -10 \text{ mAdc}, I_B = 0)$ | V _{(BR)CEO} | -30 | - | Vdc |
| Collector – Base Breakdown Voltage $(I_C = -0.1 \text{ mAdc}, I_E = 0)$ | V _{(BR)CBO} | -50 | - | Vdc |
| Emitter – Base Breakdown Voltage $(I_E = -0.1 \text{ mAdc}, I_C = 0)$ | $V_{(BR)EBO}$ | -5.0 | - | Vdc |
| Collector Cutoff Current (V _{CB} = -30 Vdc, I _E = 0) | I _{CBO} | - | -0.1 | μAdc |
| Collector–Emitter Cutoff Current (V _{CES} = -30 Vdc) | I _{CES} | - | -0.1 | μAdc |
| Emitter Cutoff Current (V _{EB} = -4.0 Vdc) | I _{EBO} | _ | -0.1 | μAdc |
| ON CHARACTERISTICS | | | | |
| DC Current Gain (Note 4) (Figure 1) $ (I_C = -1.0 \text{ mA}, V_{CE} = -2.0 \text{ V}) $ $ (I_C = -500 \text{ mA}, V_{CE} = -2.0 \text{ V}) $ $ (I_C = -1.0 \text{ A}, V_{CE} = -2.0 \text{ V}) $ $ (I_C = 2.0 \text{ A}, V_{CE} = -2.0 \text{ V}) $ | h _{FE} | 100 100 80 40 | - 300 - - | |
| Collector – Emitter Saturation Voltage (Note 4) (Figure 3) $ \begin{array}{l} (I_C=-0.5~A,~I_B=-0.05~A)\\ (I_C=-1.0~A,~I_B=0.1~A)\\ (I_C=-2.0~A,~I_B=-0.2~A) \end{array} $ | V _{CE(sat)} | - - - | -0.25 -0.30 -0.65 | V |
| Base – Emitter Saturation Voltage (Note 4) (Figure 2) $(I_C = -1.0 \text{ A}, I_B = -0.1 \text{ A})$ | V _{BE(sat)} | - | -1.2 | V |
| Base – Emitter Turn–on Voltage (Note 4) $(I_C = -1.0 \text{ A}, V_{CE} = -2.0 \text{ V})$ | V _{BE(on)} | _ | -1.1 | V |
| Cutoff Frequency ($I_C = -100 \text{ mA}$, $V_{CE} = -5.0 \text{ V}$, $f = 100 \text{ MHz}$) | f _T | 100 | - | MHz |
| Output Capacitance (f = 1.0 MHz) | Cobo | - | 15 | pF |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulsed Condition: Pulse Width = 300 msec, Duty Cycle ≤ 2%.

TYPICAL CHARACTERISTICS

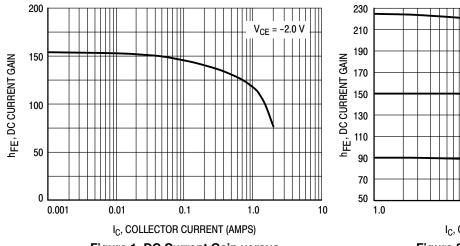


Figure 1. DC Current Gain versus Collector Current

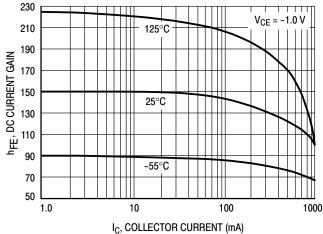


Figure 2. DC Current Gain versus Collector Current

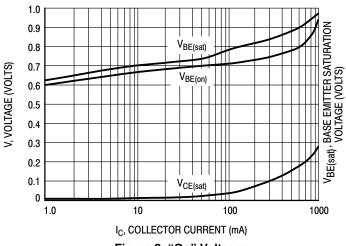


Figure 3. "On" Voltages

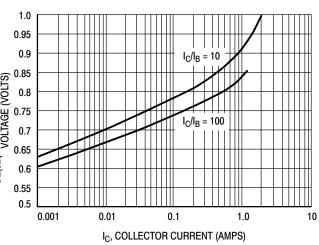


Figure 4. Base Emitter Saturation Voltage versus Collector Current

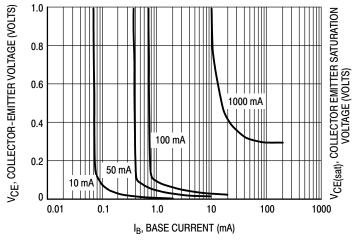


Figure 5. Collector Emitter Saturation Voltage versus Base Current

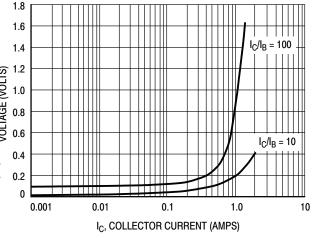


Figure 6. Collector Emitter Saturation Voltage versus Collector Current

TYPICAL CHARACTERISTICS

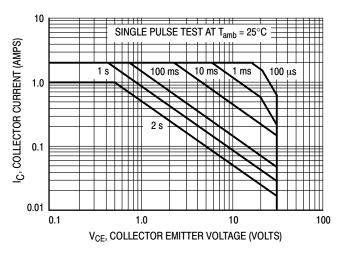


Figure 7. Safe Operating Area

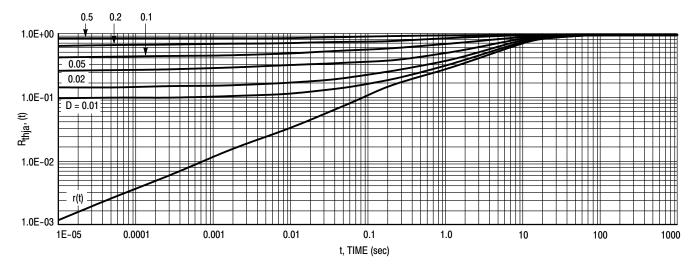
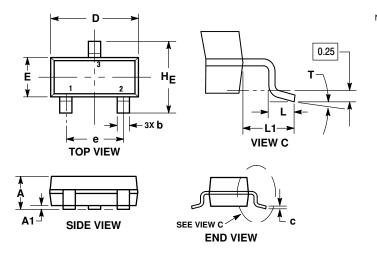


Figure 8. Normalized Thermal Response

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AR**



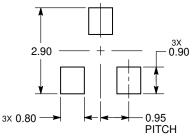
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH.
 MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,
- PROTRUSIONS, OR GATE BURRS

| | MILLIMETERS | | | INCHES | | |
|-----|-------------|------|------|--------|-------|-------|
| DIM | MIN | NOM | MAX | MIN | NOM | MAX |
| Α | 0.89 | 1.00 | 1.11 | 0.035 | 0.039 | 0.044 |
| A1 | 0.01 | 0.06 | 0.10 | 0.000 | 0.002 | 0.004 |
| b | 0.37 | 0.44 | 0.50 | 0.015 | 0.017 | 0.020 |
| С | 0.08 | 0.14 | 0.20 | 0.003 | 0.006 | 0.008 |
| D | 2.80 | 2.90 | 3.04 | 0.110 | 0.114 | 0.120 |
| E | 1.20 | 1.30 | 1.40 | 0.047 | 0.051 | 0.055 |
| е | 1.78 | 1.90 | 2.04 | 0.070 | 0.075 | 0.080 |
| L | 0.30 | 0.43 | 0.55 | 0.012 | 0.017 | 0.022 |
| L1 | 0.35 | 0.54 | 0.69 | 0.014 | 0.021 | 0.027 |
| HE | 2.10 | 2.40 | 2.64 | 0.083 | 0.094 | 0.104 |
| T | 0° | | 10° | 0° | | 10° |

STYLE 6: PIN 1. BASE

- **EMITTER**
- COLLECTOR

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

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^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.